



MLCC

Material Data Sheet

Product Family Name	SMD X7R / X5R BME B37***K
Date	28.07.2006
Version	2.0

Construction Element	Material group	Materials	CAS if applicable	mass [weight-%]			Sum [%]	Traces
				min	typical	max		
Active Part							85	
	Ceramics	Ba-titanates(96%) Dopants(4%)	12047-27-7	82	85	88		
Termination							15	
	Metal / Inner electrode	Ni(100%)	7440-02-0	2	3	4		
	Metal / Termination	Cu(80%) Ni(8%) Sn(12%)	7440-50-8 7440-02-0 7440-31-5	10	12	14		
						total:	100	

Case sizes:		L X W x H [mm]	Approx. weight [g]
B37921, B37621	0402	1.0 x 0.5 x 0.5	0.002
B37931, B37631	0603	1.6 x 0.8 x 0.8	0.006
B37941, B37641	0805	2.0 x 1.2 x 0.7	0.01
B37872, B37572	1206	3.2 x 1.6 x 0.8	0.03
B37950, B37650	1210	3.2 x 2.5 x 0.8	0.04

Company:	EPCOS OHG	Important remarks: 1) Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated (see note no. 2). 2) A list of the (legal) "... restrictions on substances ..." or materials is available at internet address of the EICTA organisation (C4E List) 3) All statements herein are based on our present knowledge. If our products are used properly, there are no risks to human beings and/or the environment.
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The component is RoHS-compatible, what means compatible with the requirements of the directives listed below and with the requirements of the provisions which will result from transformation of the directives into national law to the extent such provisions reflect the Regulations. Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive 2002/95/EC"); Commission Decision of 18 August 2005 amending Directive 2002/95/EC (2005/618/EC); Commission Decision of 13 October 2005, of 21 October 2005, of 21 February 2006 amending the Annex to Directive 2002/95/EC (2005/717/EC; 2005/747/EC, 2006/310/EC).

***) exempted by Annex 2002/95/EC (RoHS):**
5 Lead in glass of electronic components
7 (a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead.
7 (c) Lead in electronic ceramic part (e.g. piezoelectronic devices)